

Part Number: 1700820216

Series Number: 170082

Product Description: EdgeLine CoPlanar+ Connector, 15 Gbps, 0.80mm Pitch, 2.36mm PCB Thickness, 216 Circuits

**Status:** New Business Not Supported

**Product Category:** Card Edge Connectors

#### **Documents & Resources**

## **Product Environment Compliance**

## Compliance

GADSL/IMDS	Not Relevant
China RoHS	<b>©</b>
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

## Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

### Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

### **EU RoHS Certificate of Compliance**

#### **Part Details**

#### General

Status	New Business Not Supported
Category	Card Edge Connectors

Series	170082
Description	EdgeLine CoPlanar+ Connector, 15 Gbps, 0.80mm Pitch, 2.36mm PCB Thickness, 216 Circuits
Component Type	Edgecard to PCB
Product Family	EdgeLine High-Speed Connectors
Product Name	EdgeLine
Standard Based	General
UPC	884982519978

## Electrical

Current - Maximum per Contact	0.5A
Data Rate	12.5-20.0 Gbps
High Power Bay (30.0A or more)	No
Voltage - Maximum	250V AC (RMS)/DC

# Physical

Circuit Size Range	201-294 Circuits
Circuits (Loaded)	216
Circuits (maximum)	216
Color - Resin	Black
Durability (mating cycles max)	200
Edge Card Thickness	2.36mm
Entry Angle	N/A
Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	36.603/g
Orientation	Coplanar
Packaging Type	Tray
PCB Locator	No
PCB Thickness - Recommended	2.79mm
Pitch - Mating Interface	2.35mm
Pitch - Termination Interface	0.80mm

Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
(p)ower-(s)ignal Configuration	216s - 0p
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin

## **Solder Process Data**

Lead-Free Process Capability N/A	Lead-Free Process Capability	N/A
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